

# Surface-Mount TMBS<sup>®</sup> (Trench MOS Barrier Schottky) Rectifiers

## eSMP<sup>®</sup> Series



Top view

Bottom view

### SMF (DO-219AB)

Cathode  Anode

## LINKS TO ADDITIONAL RESOURCES



3D Models

## PRIMARY CHARACTERISTICS

$I_{F(AV)}$	3.0 A
$V_{RRM}$	150 V
$I_{FSM}$	40 A
$V_F$ at $I_F = 3$ A ( $T_A = 125$ °C)	0.66 V
$T_J$ max.	175 °C
Package	SMF (DO-219AB)
Circuit configuration	Single

## FEATURES

- Trench MOS Schottky technology
- Low profile package
- Ideal for automated placement
- Low forward voltage drop, low power losses
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Wave and reflow solderable
- AEC-Q101 qualified available
  - Automotive ordering code: base P/NHM3
- Compatible to SOD-123W package case outline
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## TYPICAL APPLICATIONS

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial, industrial, and automotive applications.

## MECHANICAL DATA

### Case: SMF (DO-219AB)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

**Polarity:** color band denotes the cathode end

## MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)

PARAMETER	SYMBOL	V3FM15	UNIT
Device marking code		3MC	
Maximum repetitive peak reverse voltage	$V_{RRM}$	150	V
Maximum average forward rectified current (fig.1)	$I_{F(AV)}$ <sup>(1)</sup>	2.5	A
	$I_{F(AV)}$ <sup>(2)</sup>	3.0	
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	$I_{FSM}$	40	A
Operating junction temperature range	$T_J$ <sup>(3)</sup>	-40 to +175	°C
Storage temperature range	$T_{STG}$	-55 to +175	

## Notes

<sup>(1)</sup> Free air, mounted on FR4 PCB, 2 oz. standard footprint

<sup>(2)</sup> Mounted on FR4 PCB, 2 oz. 10 mm x 10 mm copper pad area

<sup>(3)</sup> The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$

**ELECTRICAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

ELECTRONIC CHARACTERISTICS (TA = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	IF = 1.5 A	TA = 25 °C	VF (1)	0.80	-	V
	IF = 3.0 A			1.12	1.24	
	IF = 1.5 A	TA = 125 °C		0.58	-	
	IF = 3.0 A			0.66	0.74	
Reverse current	VR = 100 V	TA = 25 °C	IR (2)	0.4	-	µA
		TA = 125 °C		500	-	
	VR = 150 V	TA = 25 °C		-	85	
		TA = 125 °C		900	3000	
Typical junction capacitance	4.0 V, 1 MHz		CJ	150	-	pF

**Notes**(1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle(2) Pulse test: Pulse width  $\leq 5\text{ ms}$ **THERMAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

PARAMETER	SYMBOL	V3FM15	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)(2)}$	125	$^{\circ}\text{C/W}$
	$R_{\theta JM}^{(3)}$	22	

**Notes**(1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ (2) Device mounted on FR4 PCB, 2 oz. standard footprint, thermal resistance  $R_{\theta JA}$  – junction-to-ambient(3) Device mounted on 10 mm x 10 mm pad size area footprint; thermal resistance  $R_{\theta JM}$  – junction-to-mount**ORDERING INFORMATION** (Example)

PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V3FM15-M3/H	0.015	H	3000	7" diameter plastic tape and reel
V3FM15-M3/I	0.015	I	10 000	13" diameter plastic tape and reel
V3FM15HM3/H <sup>(1)</sup>	0.015	H	3000	7" diameter plastic tape and reel
V3FM15HM3/I <sup>(1)</sup>	0.015	I	10 000	13" diameter plastic tape and reel

**Note**

(1) AEC-Q101 qualified

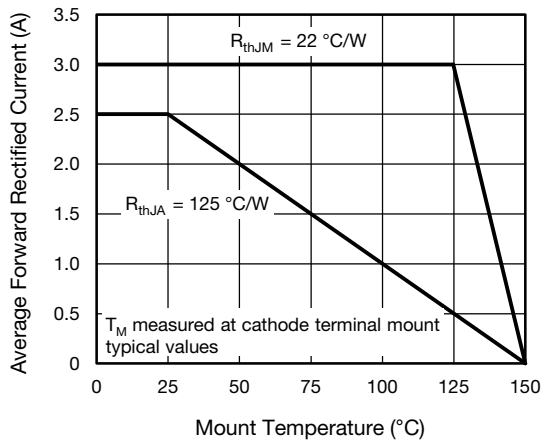
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)


Fig. 1 - Maximum Forward Current Derating Curve

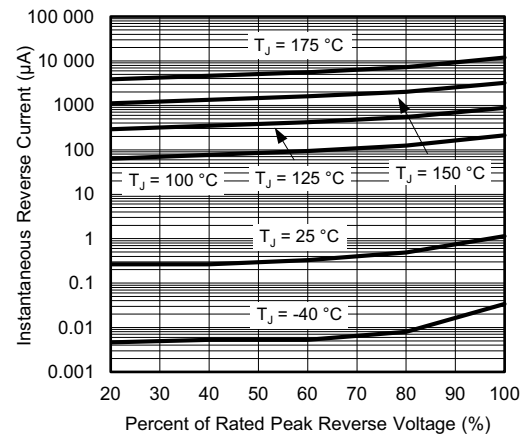


Fig. 4 - Typical Reverse Leakage Characteristics

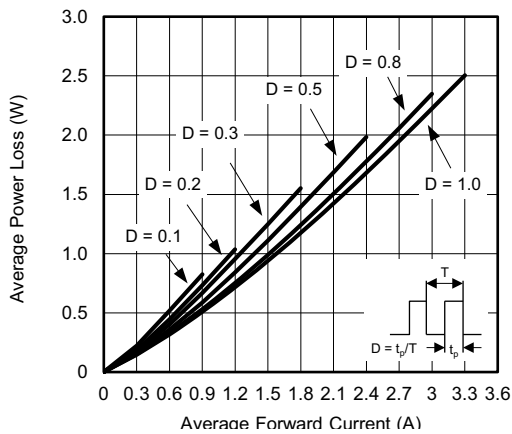


Fig. 2 - Average Power Loss Characteristics

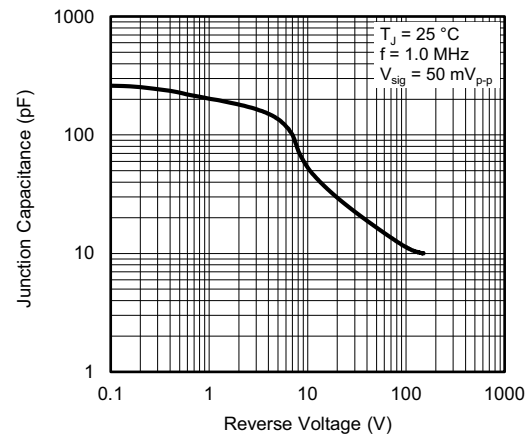


Fig. 5 - Typical Junction Capacitance

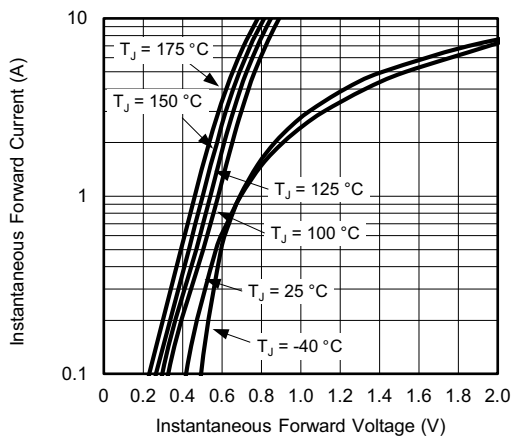


Fig. 3 - Typical Instantaneous Forward Characteristics

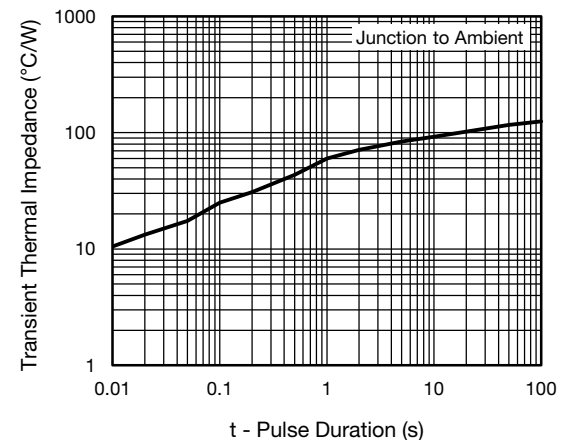
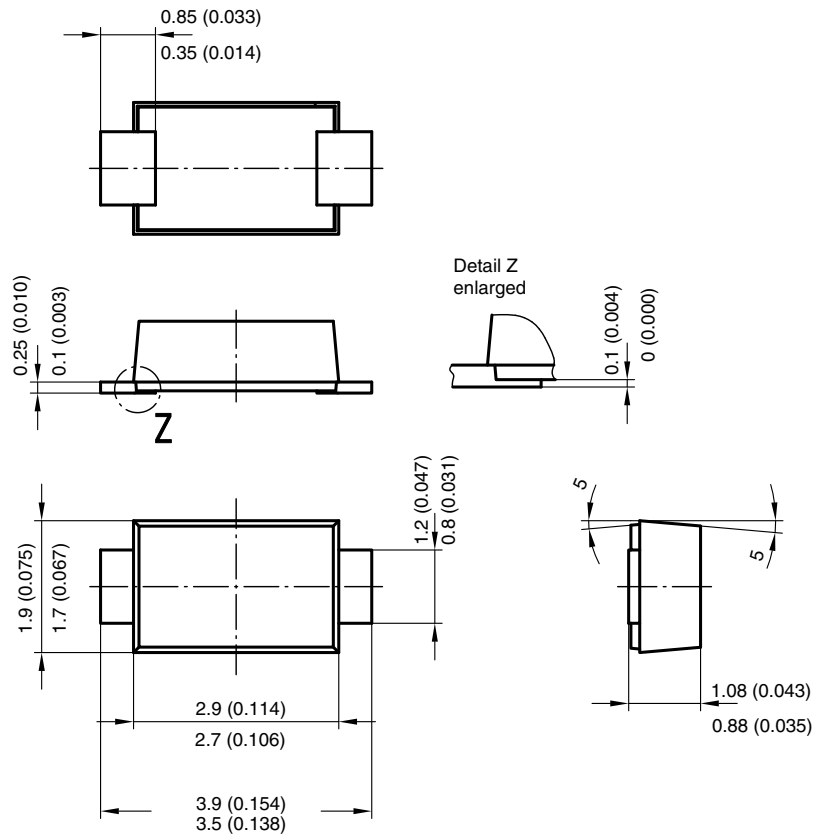


Fig. 6 - Typical Transient Thermal Impedance

**PACKAGE OUTLINE DIMENSIONS** in millimeters (inches)


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